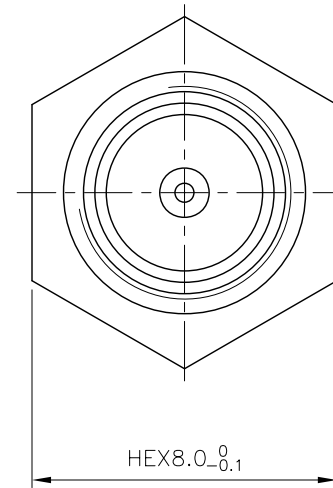
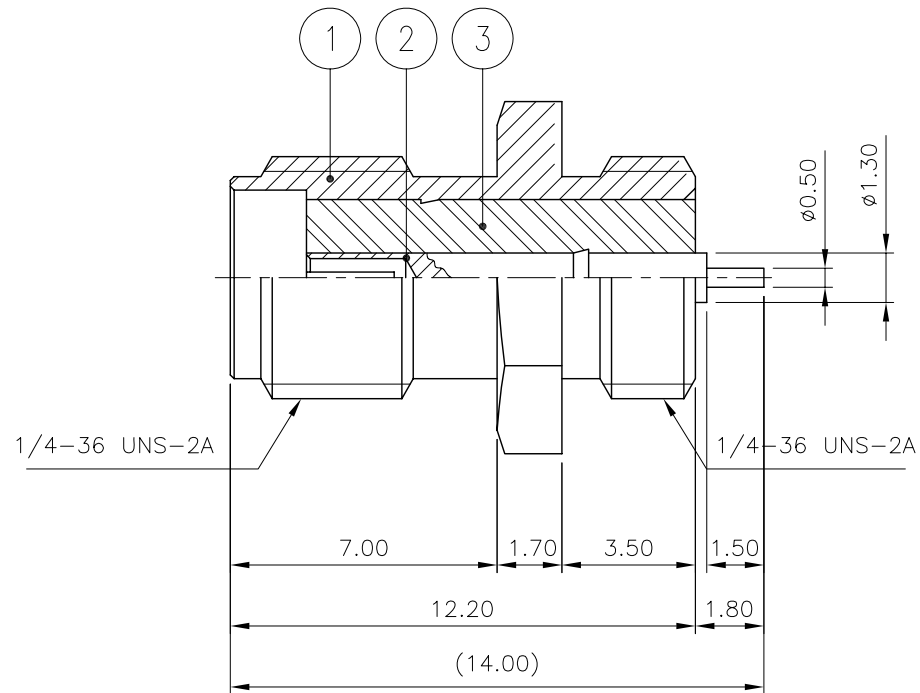


REVISION					
REV	DESCRIPTION	DRAWN	APPR	DATE	
IR	Initial Registration	M.H.SONG	I.C.KIM	2001.02.07.	
1	[설번No.연구2006-149]신뢰성 향상(CONTACT 닙시턱 추가)	I.C.KIM	S.J.YOUN	2006.07.27.	
2	[설번No.201405-0004]신뢰성 향상(BODY 닙시턱 추가 및 INSULATOR 구성 변경)	M.H.SONG	I.C.KIM	2014.05.13.	



3	INSULATOR	1	TEFLON		DIN02390-N/1 DIN00128-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT00209-5/1
1	BODY	1	MBsBD	Gold Plate	DBD00314-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2014. 05. 13.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	-	KJ COMTECH CO.,LTD. TITLE SMA50 SOLDER END JB(F/F)
		DRAWN BY	M.H.SONG	
FINISH		SCALE	5/1	A4 DWG NO. CN00111-7/1 REVISION 2 SHEET 1 of 1
		UNIT	mm	